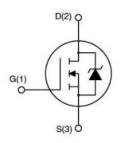


#### **Feature**

• 60V,36A

$$\begin{split} &R_{DS\ (ON)} < 16 \text{m}\ \Omega\ @V_{GS} = 10V & TYP: 13.2\ \text{m}\ \Omega \\ &R_{DS\ (ON)} < 20 \text{m}\ \Omega\ @V_{GS} = 4.5V & TYP: 15.2\ \text{m}\ \Omega \end{split}$$

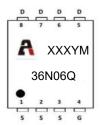
- Advanced Trench Technology
- Lead free product is acquired
- Excellent R DS (ON) and Low Gate Charge



**Schematic Diagram** 

## **Application**

- PWM applications
- Load Switch
- Power management



**Marking and pin Assignment** 

# **Package Marking and Ordering Information**

Device Marking	evice Marking Device		Reel Size	Tape width	Quantity (PCS)	
36N06Q	AP36N06Q	PDFN3X3	13 inch	-	5000	

# ABSOLUTE MAXIMUM RATINGS (T<sub>J</sub>=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>G</sub> S	±20	V
Continuous Drain Current (T <sub>c</sub> =25℃)	I <sub>D</sub>	36	А
Continuous Drain Current (T <sub>c</sub> =100℃)	I <sub>D</sub>	23	А
Pulsed Drain Current (1)	<b>I</b> DM	144	А
Single Pulsed Avalanche Energy (2)	Eas	60	mJ
Power Dissipation	PD	41	W
Thermal Resistance from Junction to Case	Rejc	3.0	°C/W
Thermal Resistance from Junction to Ambient	Reja	56	°C/W
Junction Temperature	TJ	150	$^{\circ}$
Storage Temperature	T <sub>STG</sub>	-55~ +150	${\mathbb C}$



## MOSFET ELECTRICAL CHARACTERISTICS(TJ=25℃ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Туре	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =-250µA	60	-	-	V
Zero gate voltage drain current	IDSS	V <sub>DS</sub> =60V, V <sub>GS</sub> = 0V	-	-	1	μΑ
Gate-body leakage current	Igss	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage(3)	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.6	2.2	V
Duning (3)	_	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	13.2	16	- mΩ
Drain-source on-resistance <sup>(3)</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	-	15.2	20	
Forward tranconductance <sup>(3)</sup>	<b>g</b> FS	V <sub>DS</sub> =5V, I <sub>D</sub> =10A	20	-	-	S
Dynamic characteristics	•		•			
Input Capacitance	C <sub>iss</sub>		-	2600	-	pF
Output Capacitance	Coss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f =1MHz	-	125	-	
Reverse Transfer Capacitance	Crss	1	-	105	-	
Switching characteristics			•	•		
Turn-on delay time	t <sub>d(on)</sub>		-	4	-	ns
Turn-on rise time	t <sub>r</sub>	V <sub>DD</sub> =30V, I <sub>D</sub> =20A	-	8	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{GS}$ =10V, $R_{G}$ =1.8 $\Omega$	-	27	-	
Turn-off fall time	t <sub>f</sub>		-	20	-	
Total Gate Charge	Qg	\(\text{PQ-QQ\\  \text{P}-QQ\\ \)	-	51	-	nC
Gate-Source Charge	Qgs	VDS=30V, ID=20A,	-	7.9	-	
Gate-Drain Charge	Qgd	- VGS=10V	-	8.1	-	
Source-Drain Diode characteristics	•		•	•		
Diode Forward voltage <sup>(3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	-	-	1.2	V
Diode Forward current <sup>(4)</sup>	Is		-	-	36	Α
Body Diode Reverse Recovery Time	trr	T <sub>J</sub> =25° , IF=20A,di/dt=100A/us		21		ns
Body Diode Reverse Recovery Charge	Qrr	T <sub>J</sub> =25°, IF=20A,di/dt=100A/us		18		nc

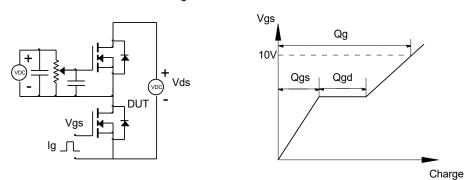
#### Notes:

- 1. Repetitive Rating: pulse width limited by maximum junction temperature
- 2. EAS Condition: $T_J$ =25  $^{\circ}$ C, $V_{DD}$ =30V, $R_G$ =25  $^{\Omega}$ ,L=0.5mH
- 3. Pulse Test: pulse width≤300µs, duty cycle≤0.5%
- 4. Surface Mounted on FR4 Board,t≤10 sec

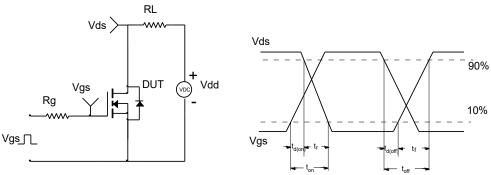


## **Test Circuit**

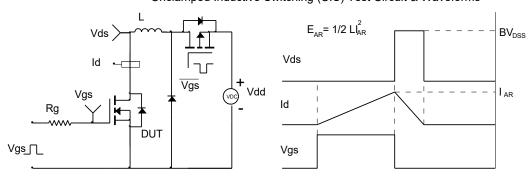
#### Gate Charge Test Circuit & Waveform



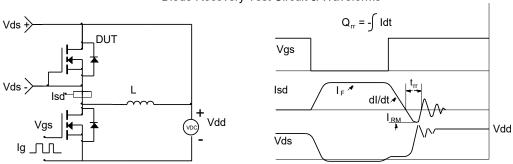
Resistive Switching Test Circuit & Waveforms



#### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



#### Diode Recovery Test Circuit & Waveforms





### **Typical Performance Characteristics**

Figure1: Output Characteristics

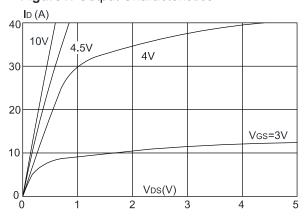


Figure 2: Typical Transfer Characteristics

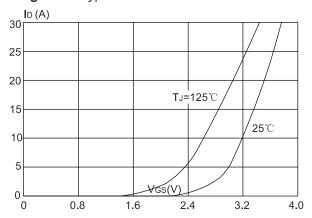


Figure 3:On-resistance vs. Drain Current

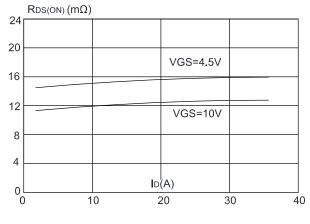


Figure 4: Body Diode Characteristics

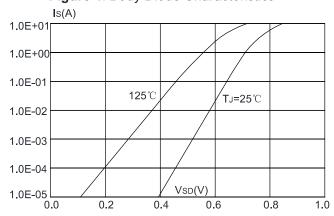


Figure 5: Gate Charge Characteristics

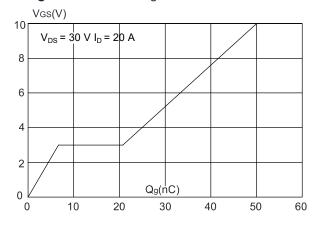
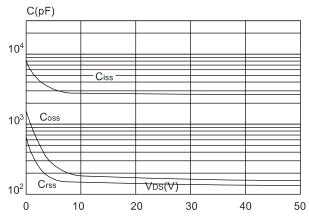


Figure 6: Capacitance Characteristics





### **Typical Performance Characteristics**

**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature

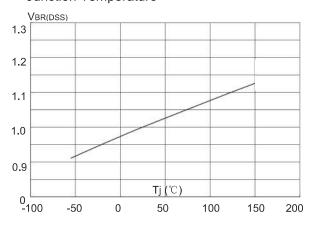
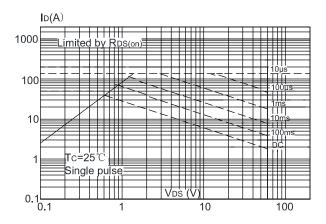
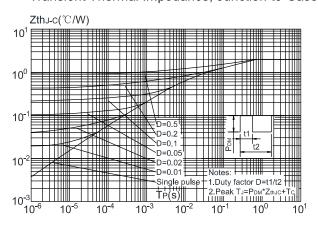


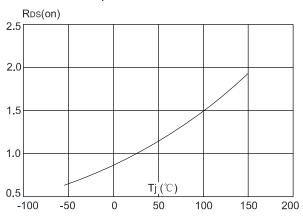
Figure 9: Maximum Safe Operating Area



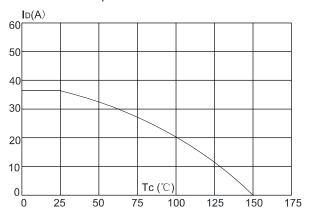
**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Figure 8:** Normalized on Resistance vs. Junction Temperature

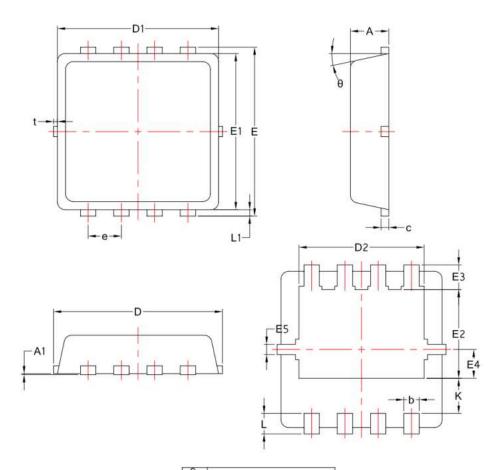


**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature





# PDFN3X3 Package Information



S	COMMON						
M B	MM						
M B O L	MIN	NOM	MAX				
Α	0.70	0.75	0.85				
A1	1	/	0.05				
b	0.20	0.30	0.40				
С	0.10	0.152	0.25				
D	3.15	3.30	3.45				
D1	3.00	3.15	3.25				
D2	2.29	2.45	2.65				
Е	3.15	3.30	3.45				
E1	2.90	3.05	3.20				
E2	1.54	1.74	1.94				
E3	0.28	0.48	0.65				
E4	0.37	0.57	0.77				
E5	0.10	0.20	0.30				
е	0.60	0.65	0.70				
K	0.59	0.69	0.89				
L	0.30	0.40	0.50				
L1	0.06	0.125	0.20				
t	0	0.075	0.13				
θ	10°	12°	14°				

### **AP36N06Q**





### **Revision History**

Revision	Release	Remark
V1.0	2024/01/24	Initial Release

#### **Disclaimer**

The information given in this document describes the independent performance of the product, but similar performance is not guaranteed under other working conditions, and cannot be guaranteed when installed with other products or equipment. To achieve the required performance of the product in actual scenarios, the customer should conduct a complete application test to assess the functionality of the product.

Allpower assumes no responsibility for equipment failures result from using products at values that exceed the ratings, operating conditions, or other parameters listed in the product specifications.

The product described in this specification is not applicable for aerospace or other applications which requires high reliability. Customers using or selling these products for use in medical, life-saving, or life-sustaining applications do so at their own risk and agree to fully indemnify.

Due to product or technical improvements, the information described or contained herein may be changed without prior notice.